

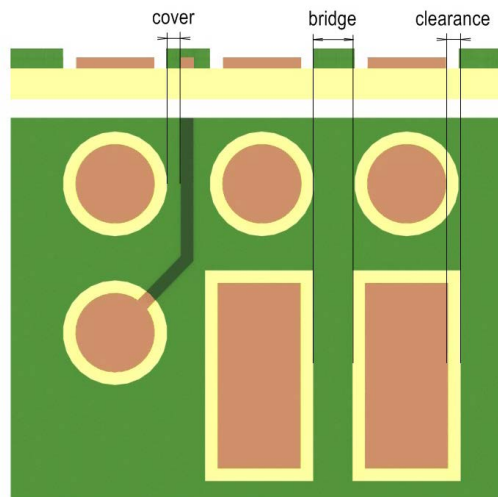
# Design Rules

## Solder mask – green color

	standard	minimum
clearance	40 µm	25 µm (BGA)
IO bridge	105 µm	100 µm
cover	75 µm	50 µm

## Solder mask – others colors

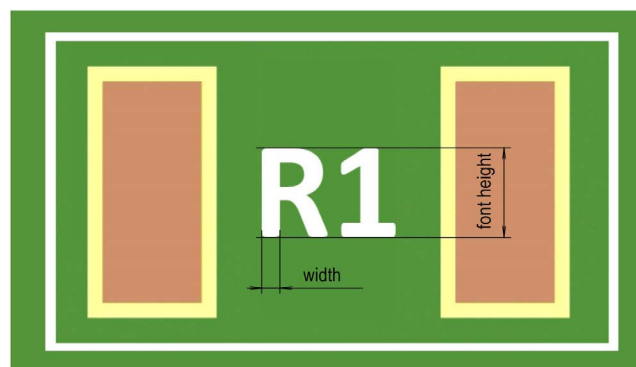
	standard	minimum
clearance	60 µm	40 µm
IO bridge	150 µm	140 µm
cover	75 µm	60 µm



## Silkscreen parameters

font height	width
1200 µm	130 µm
1500 µm	150 µm
1800 µm	180 µm

For service printing in a solder mask, the minimum font size allowed is **120 µm for ENIG, 250 µm for HAL**.

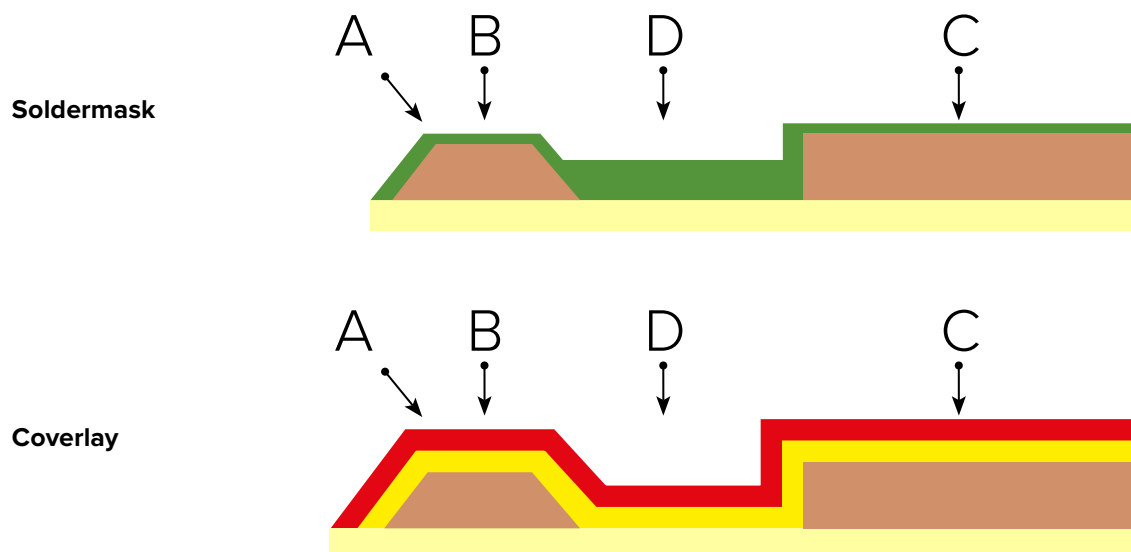


# Design Rules

## Via filling with solder mask

	standard
max. drill	300 µm

## Solder mask thickness



Mask	A (µm)	B (µm)	C (µm)	D (µm)
Green	5–15	5–15	10–20	25–35
Colored	15–25	20–30	25–35	35–40
Flex SM green	10–20	10–20	10–20	35–40
Pyralux LF coverlay	25+25	25+25	25+25	25+25 (adhesive)